EE143 Week 6: Pre-Lab Quiz

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	ament, please draw a top view of ok like for this week's mask and	
(2) Order the following ste step):() Etch the oxide	eps for this weeks lab(1 for the fi	irst step, through 5 for last
() Expose the photoresist() Strip the photoresist		
() Develop the photoresis() Etch the polysilicon	t	
(3) Which of these is what BHF etch)? (top layer=photoresist	a normal wet-etched film looks middle layer=oxide bulk=sil	
()	()	()

(4) What can be done to help all the 2-micron gates survive the steps we will do in the lab this week?

(5) Why do exposure times vary with substrate material?
(6) What do we etch the polysilicon with? What is the nominal polysilicon etch rate? Using the nominal etch rate above, assuming 3500Å of poly, and using a 10% overetch, how long should we etch the poly?
(7) Why do we do an oxide etch after the polysilicon etch?
(8) Show how one of your MOSFETs will look after this week's lab (draw cross section)?